WHAT IS CLAIMED IS:

1. An electroplating system comprising:

an electroplating chamber; and

a replenish assembly fluidly coupled with the electroplating chamber, the replenish assembly comprising:

an anolyte compartment housing anode material, the anolyte compartment having a first compartment section in which the anode material is housed and a second compartment section separated from the first compartment section by a divider, wherein the divider fluidly separates the first compartment section from the second compartment section,

a second compartment fluidly coupled with the electroplating chamber and electrically coupled with the anolyte compartment, wherein the second compartment includes a catholyte and

a third compartment electrically coupled with the second compartment, the third compartment comprising an inert cathode.

2. The electroplating system of claim 1, further comprising:

a voltage source coupling the anode material with the inert cathode.

3. The electroplating system of claim 1, wherein the third compartment includes a thiefolyte.

4. The electroplating system of claim 3, wherein the third compartment is fluidly coupled with the electroplating chamber to deliver thiefolyte between the third compartment and the electroplating chamber, and wherein the second compartment is fluidly coupled with the electroplating chamber.

5. The electroplating system of claim 1, further comprising:

a first ionic membrane positioned between the second compartment section of the anolyte compartment and the second compartment; and

a second ionic membrane positioned between the second compartment and the third compartment.

6. The electroplating system of claim 5, wherein the second ionic membrane is a monovalent membrane.

7. The electroplating system of claim 1, further comprising:

a pump fluidly coupled between the first compartment section of the anolyte compartment and the second compartment section of the anolyte compartment.

8. The electroplating system of claim 7, wherein the pump is operable in a first setting to flow anolyte from the first compartment section of the anolyte compartment to the second compartment section of the anolyte compartment.

9. The electroplating system of claim 8, wherein a fluid path is defined about the divider so that anolyte flows from the second compartment section of the anolyte compartment to the first compartment section of the anolyte compartment when the pump is operating in the first setting.

10. The electroplating system of claim 8, wherein the pump is operable in a second setting to fully drain the anolyte from the second compartment section of the anolyte compartment.

11. The electroplating system of claim 1, further comprising:

an insert seated in the second compartment, the insert defining at least one fluid channel along the insert.

12. The electroplating system of claim 1, further comprising:

a compartment disposed within the first compartment section of the first compartment, the compartment housing the anode material.

13. The electroplating system of claim 1, wherein the divider is an ionic membrane fluidly isolating a flow path between the first compartment section of the first compartment to the second compartment section of the first compartment.

14. A method of operating an electroplating system, the method comprising:

driving a voltage through a replenish assembly, the replenish assembly comprising:

an anolyte compartment housing anode material, the anolyte compartment having a first compartment section in which the anode material is housed

and a second compartment section separated from the first compartment section by a divider, wherein the divider fluidly separates the first compartment section from the second compartment section,

a second compartment fluidly coupled with an electroplating chamber and electrically coupled with the anolyte compartment, wherein the second compartment includes a catholyte, and

a third compartment electrically coupled with the second compartment, the third compartment comprising an inert cathode, wherein the voltage is driven from the anode material to the inert cathode through the first compartment section of the first compartment, the second compartment section of the first compartment, the second compartment, and the third compartment; and

providing ions of the anode material to a catholyte flowing through the second compartment.

15. The method of operating an electroplating system of claim 14, further comprising:

reversing the voltage between the anode material and the inert cathode; and

removing plated anode material from the inert cathode.

16. The method of operating an electroplating system of claim 14, further comprising:

pumping an anolyte from the second compartment section of the anolyte compartment to the first compartment section of the anolyte compartment to drain the second compartment section of the anolyte compartment.

17. The method of operating an electroplating system of claim 16, wherein the replenish assembly further comprises:

a first ionic membrane positioned between the second compartment section of the anolyte compartment and the second compartment; and

a second ionic membrane positioned between the second compartment and the third compartment.

18. The method of operating an electroplating system of claim 17, wherein the pumping maintains the first ionic membrane in fluid contact only with the catholyte.

19. An electroplating system comprising:

an electroplating chamber; and

a replenish assembly fluidly coupled with the electroplating chamber, the replenish assembly comprising:

an anoltye compartment housing anode material and an anolyte, the anolye compartment having a first compartment section in which the anode material is housed and a second compartment section separated from the first compartment section by a divider, wherein the divider fluidly separates the first compartment section from the second compartment section, and wherein a fluid circuit is defined between the first compartment section and the second compartment section,

a second compartment fluidly coupled with the electroplating chamber and electrically coupled with the anolyte compartment, wherein the second compartment contains catholyte,

a first ionic membrane positioned between the second compartment section of the anolyte compartment and the second compartment,

a third compartment electrically coupled with the second compartment, the third compartment comprising an inert cathode, wherein the third compartment comprises an acid thiefolyte, and

a second ionic membrane positioned between the second compartment and the third compartment.

20. The electroplating system of claim 19, wherein the divider is a third ionic membrane.